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SEP 19 2002 3:27PM HAYNES BEFFEL & WOLFELD L 650-712-0263

M. Brunson

9/25/02

Atty. Docket No. CPAC 1013-1  
Appl. No. 09/893,356

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Marcos KARNEZOS, *et al.*

Application No.: 09/893,356

Filed: June 26, 2001

Title: **Integral heatsink ball grid array**

)  
) Examiner: Ngan V. NGO  
)  
) Group Art Unit: 2814  
)  
) Date: September 19, 2002

CERTIFICATE OF FACSIMILE TRANSMISSION

I hereby certify that this correspondence is being facsimile transmitted to the United States Patent and Trademark Office, TC 2800 at fax no. 703 872-9318 on September 19, 2002.

Signed

Linda Shaw

COMMISSIONER FOR PATENTS  
WASHINGTON, D.C. 20231

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AMENDMENT

TECHNOLOGY CENTER 2800

Dear Sir:

Responsive to the Office Action mailed June 19, 2002, kindly amend the application as follows.

In the Claims

Please amend claims 1 and 3 as shown on the attached "Attachment under Rule 1.121", as follows.

1. (Amended) A semiconductor device package comprising:

a semiconductor device affixed to an upper surface of a substrate, the semiconductor device having an upper surface;

A  
a mold cap covering at least the upper surface of the semiconductor device, the mold cap having an upper surface;

a heat spreader affixed to at least a portion of the upper surface of the mold cap, the heat spreader being entirely external to the mold cap.